

ABSTRACT

The utility model provides a transmitter optical subassembly and an optical module. The transmitter optical subassembly comprises a core column, a secondary column and a first substrate. The first substrate is provided with a first conductive pattern layer, a transmitter optical chip and a matching resistor. The first conductive pattern layer comprises a radio-frequency signal transmission line, a first pad and a second pad. The transmitter optical chip is electrically connected to the first pad and the second pad respectively, the second pad is a ground pad, the matching resistor is electrically connected to the radio-frequency signal transmission line and the first pad respectively, and the matching resistor and the first pad are both provided close to the transmitter optical chip, thereby reducing a distance between the matching resistor and the transmitter optical chip, optimizing the electrical port reflection of radio-frequency optical transmission, reducing the link signal reflection, optimizing the gain flatness, improving the radio-frequency signal transmission performance, and facilitating packaging of transistor shapes.

Fig.2